



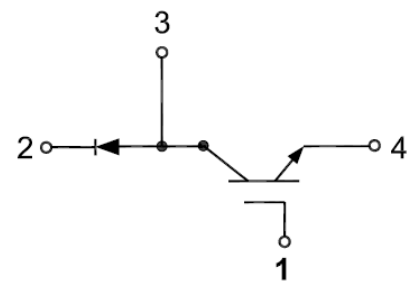
GT100CU120B5H

IGBT Module

Features:

- Field Stop Trench Gate IGBT
- Short Circuit Rated >10 μ s
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested (2 \times I_c)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement

Circuit Diagram



Applications:

- Welding
- HEV Inverter
- Industrial Motor Drives
- UPS

IGBT, Chopper

Maximum Rated Values of IGBT ($T_C=25^\circ\text{C}$ unless otherwise specified)

V _{CES}	Collector-Emitter Blocking Voltage		1200	V
V _{GES}	Gate-Emitter Voltage		± 20	V
I _c	Continuous Collector Current	T _C =80 $^\circ\text{C}$	100	A
		T _C =25 $^\circ\text{C}$	200	A
I _{CM}	Repetitive Peak Collector Current	T _J =150 $^\circ\text{C}$	200	A
t _{SC}	Short Circuit Withstand Time		>10	μ s
P _D	Maximum Power Dissipation (IGBT)	T _C =25 $^\circ\text{C}$ T _{J,max} =150 $^\circ\text{C}$	604	W



Electrical Characteristics of IGBT ($T_C=25^\circ\text{C}$ unless otherwise specified)

Static Characteristics

Symbol	Description	Conditions	Min	Typ	Max	Unit
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=1\text{mA}, V_{CE}=V_{GE}$	5.0	5.8	6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=100\text{A}, V_{GE}=15\text{V}$	$T_J=25^\circ\text{C}$	1.70	2.00	V
			$T_J=125^\circ\text{C}$	2.00		V
			$T_J=150^\circ\text{C}$	2.10		V
I_{CES}	Collector-Emitter Leakage Current	$V_{GE}=0\text{V}, V_{CE}=V_{CES}, T_J=25^\circ\text{C}$			1	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}, V_{CE}=0\text{V}, T_J=25^\circ\text{C}$			200	nA
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=100\text{kHz}, T_J=25^\circ\text{C}$		8.87		nF
C_{oes}	Output Capacitance			0.61		nF
C_{res}	Reveres Transfer Capacitance			0.24		nF

Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600\text{V}, I_C=100\text{A}, R_{Gon}=10\Omega, V_{GE}=\pm 15\text{V}, \text{Inductive Load}$	$T_J=25^\circ\text{C}$	283		ns	
			$T_J=125^\circ\text{C}$	297			
			$T_J=150^\circ\text{C}$	293			
t_r	Rise Time		$T_J=25^\circ\text{C}$	83		ns	
			$T_J=125^\circ\text{C}$	89			
			$T_J=150^\circ\text{C}$	96			
$t_{d(off)}$	Turn-off Delay Time		$V_{CC}=600\text{V}, I_C=100\text{A}, R_{Goff}=10\Omega, V_{GE}=\pm 15\text{V}, \text{Inductive Load}$	$T_J=25^\circ\text{C}$	186		ns
				$T_J=125^\circ\text{C}$	205		
				$T_J=150^\circ\text{C}$	213		
t_f	Fall Time	$T_J=25^\circ\text{C}$		344		ns	
		$T_J=125^\circ\text{C}$		466			
		$T_J=150^\circ\text{C}$		468			
E_{on}	Turn-on Switching Loss	$V_{CC}=600\text{V}, I_C=100\text{A}, R_{Gon}=10\Omega, V_{GE}=\pm 15\text{V}, di/dt=867\text{A}/\mu\text{s} (T_J=150^\circ\text{C}) \text{ Inductive Load}$		$T_J=25^\circ\text{C}$	7.6		mJ
				$T_J=125^\circ\text{C}$	12.3		
				$T_J=150^\circ\text{C}$	13.4		



E _{off}	Turn-off Switching Loss	V _{CC} =600V, I _C =100A, R _{Goff} =10Ω, V _{GE} =±15V, du/dt=3812V/μs (T _J =150°C) Inductive Load	T _J =25°C		7.1		mJ
			T _J =125°C		10.6		
			T _J =150°C		11.1		
Q _g	Total Gate Charge	V _{GE} =+15V...-15V	T _J =25°C		410		nC
R _{gint.}	Internal Gate Resistor		T _J =25°C		6		Ω
RBSOA	I _C =200A, V _{CC} =1050V, V _p =1200V, R _G =10Ω, V _{GE} =+15V to 0V, T _J =150°C			Trapezoid			
SC data	V _{CC} =600V, R _{Gon} =10Ω, R _{Goff} =10Ω, t _p =10us, V _{GE} =+/-15V, T _J =125°C				372		A
R _{θJC}	IGBT Thermal Resistance: Junction-To-Case (per IGBT)					0.207	°C/W

Diode, Chopper

Maximum Rated Values of Diode (T_C=25°C unless otherwise specified)

V _{RRM}	Repetitive Peak Reverse Voltage	1200	V
I _F	Diode Continuous Forward Current	100	A
I _{FM}	Diode Maximum Forward Current	200	A

Electrical Characteristics of Diode (T_C=25°C unless otherwise specified)

Symbol	Description	Conditions	Min	Typ	Max	Unit	
V _{FM}	Forward Voltage	I _F =100A	T _J =25°C		1.65		V
			T _J =125°C		1.70		
			T _J =150°C		1.70		
t _{rr}	Reverse Recovery Time	I _F =100A, -diF/dt=1167A/μs(T _J =150°C), V _R =600V, V _{GE} =-15V	T _J =25°C		319		ns
			T _J =125°C		473		
			T _J =150°C		597		
I _{rr}	Peak Reverse Recovery Current	I _F =100A, -diF/dt=1167A/μs(T _J =150°C), V _R =600V, V _{GE} =-15V	T _J =25°C		73.4		A
			T _J =125°C		87.5		
			T _J =150°C		90.6		



Q _{rr}	Reverse Recovery Charge	I _F =100A, -diF/dt=1167A/μs(T _J =150°C), V _R =600V, V _{GE} =-15V	T _J =25°C		10.8		μC
			T _J =125°C		18.6		
			T _J =150°C		21.9		
E _{rec}	Reverse Recovery Energy		T _J =25°C		4.15		mJ
			T _J =125°C		6.89		
			T _J =150°C		8.37		
R _{θJC}	Diode Thermal Resistance: Junction-To-Case (per Diode)					0.251	°C/W

Module

Symbol	Description		Min	Typ	Max	Unit
V _{iso}	Isolation Voltage (All Terminals Shorted)	f = 50Hz, 30s	4500			V
Material of Module Base plate			Copper			
Internal Isolation			Al ₂ O ₃			
T _J	Maximum Junction Temperature				150	°C
T _{JOP}	Maximum Operating Junction Temperature Range		-40		+125	°C
T _{stg}	Storage Temperature		-40		+125	°C
CTI	Comparative Tracking Index		200			
R _{θCS}	Case-To-Sink Thermally (Conductive Grease Applied)				0.21	°C/W
T	Power Terminals Screw(M4)		1.1		1.5	N·m
T	Mounting Screw(M4)		1.1		1.5	N·m
G	Weight			30		g



Ordering Information Table

Device code

G	T	100	CU	120	B5	H
①	②	③	④	⑤	⑥	⑦

- ① - IGBT Module
- ② - Field Stop Trench Gate IGBT
- ③ - Rated Current (100=100A)
- ④ - Circuit Configuration: Chopper (Diode on High Side)
- ⑤ - Rated Voltage (120=1200V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)

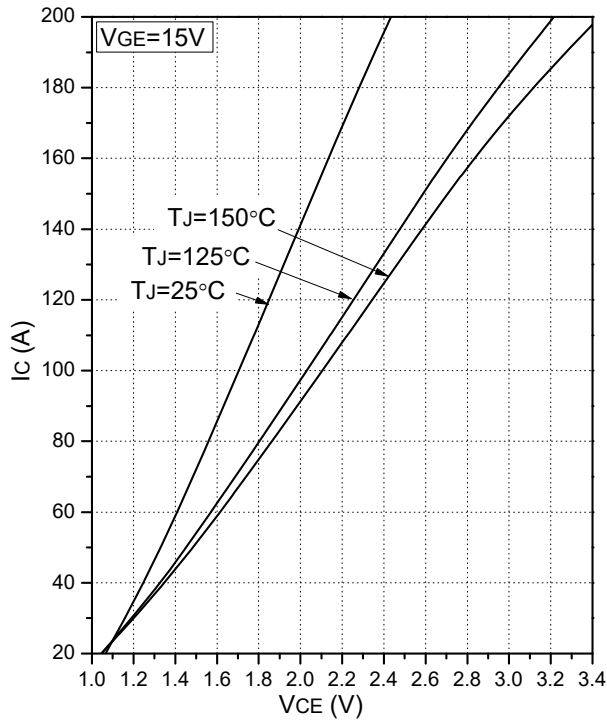


Fig.1 Typical Saturation Voltage Characteristics

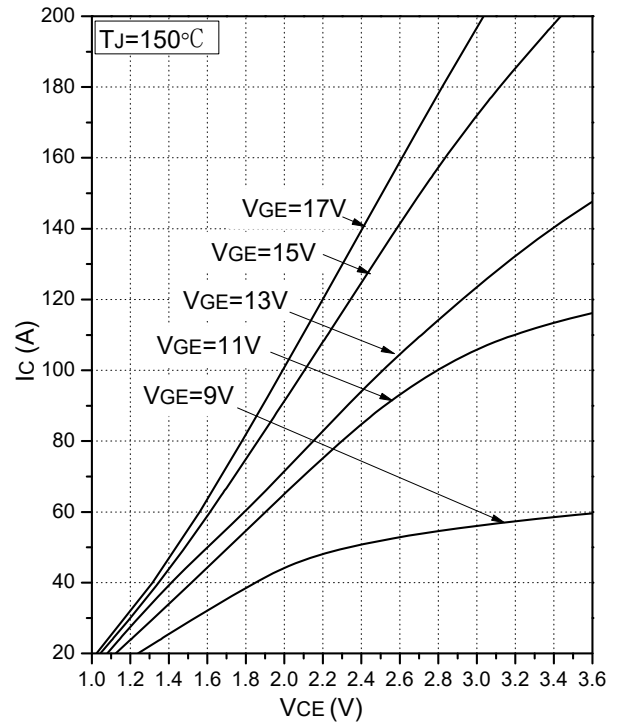


Fig.2 Typical Output Characteristics

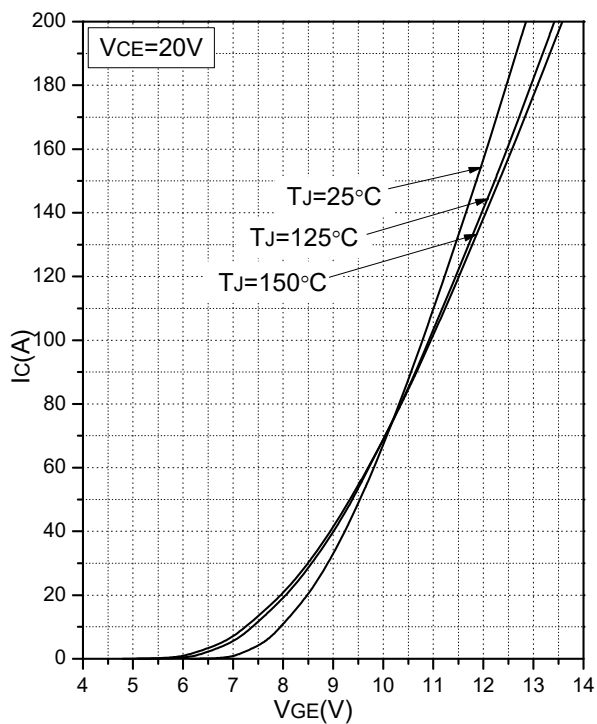


Fig.3 Transfer Characteristic

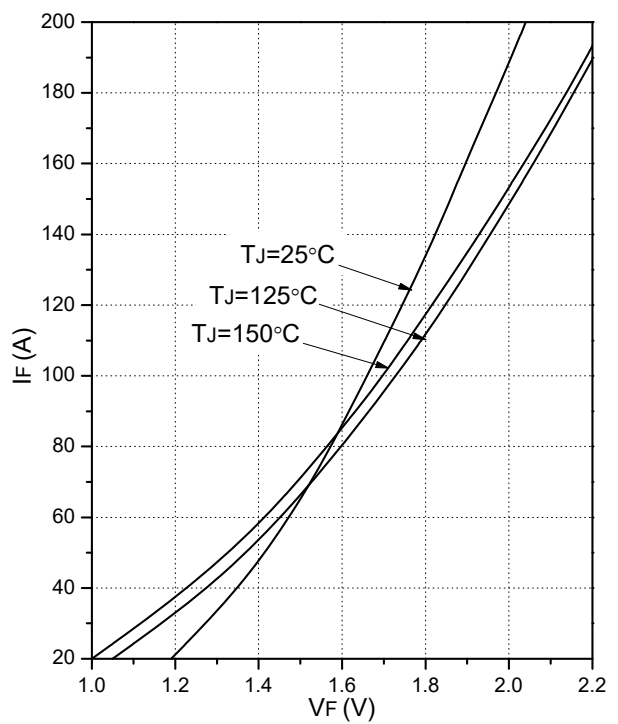


Fig.4 Forward Characteristics of Diode

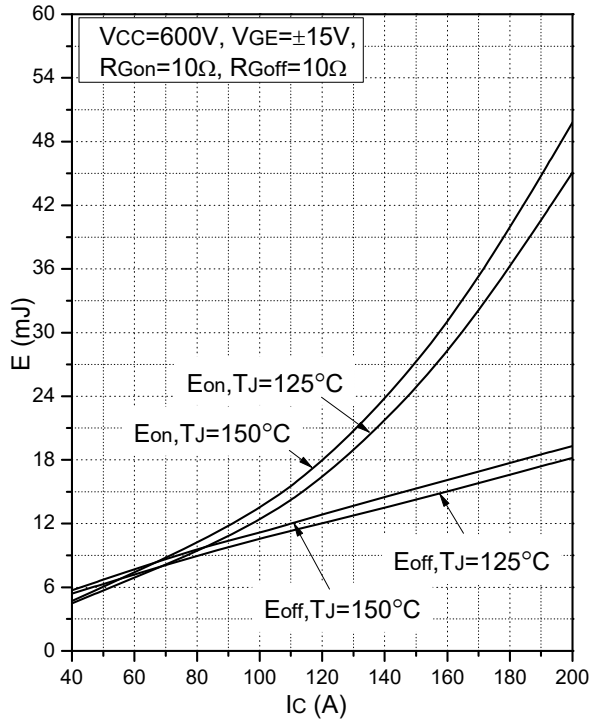


Fig.5 Typical Switching Loss vs. Collector Current

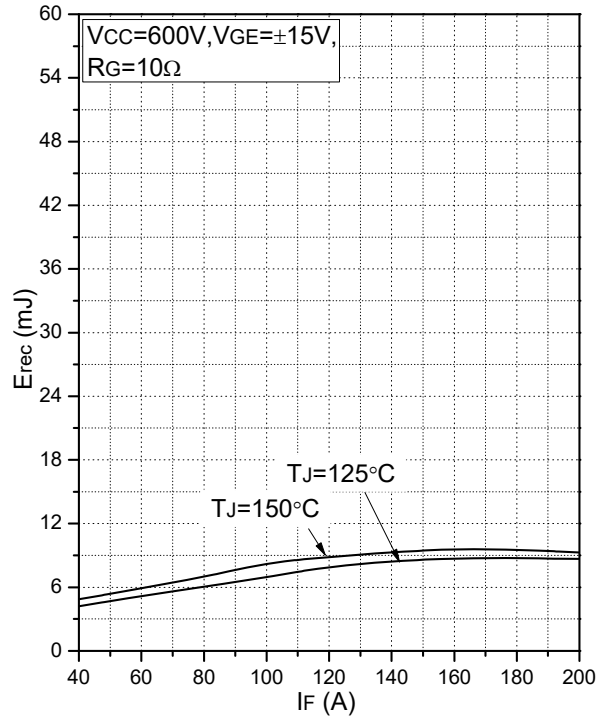


Fig.6 Typical Switching Loss vs. Forward Current

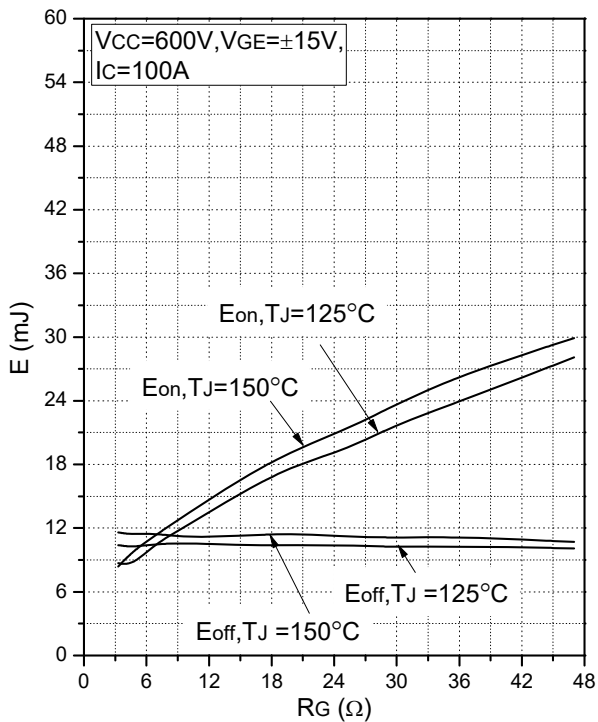


Fig.7 Typical Switching Loss vs. Gate Resistance

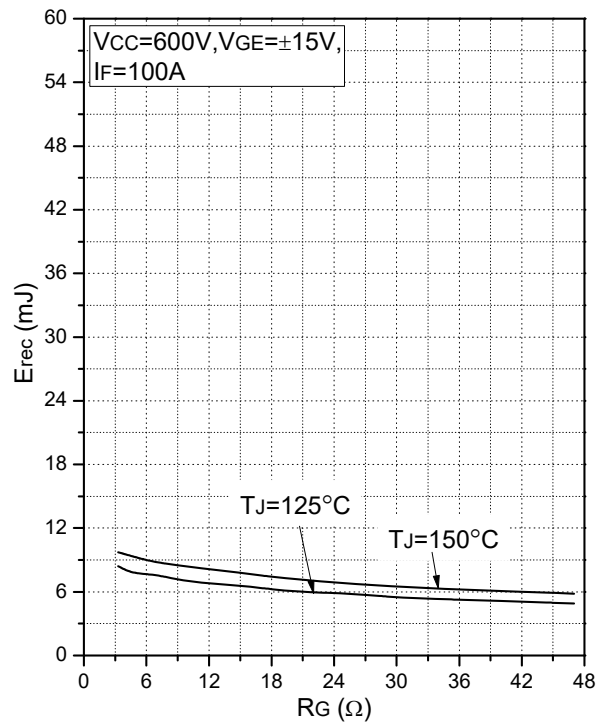


Fig.8 Typical Switching Loss vs. Gate Resistance

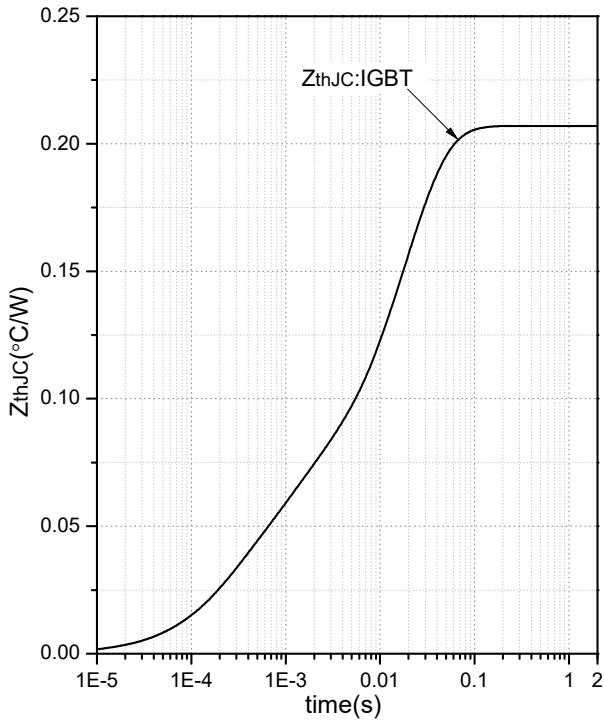


Fig.9 Transient Thermal Impedance (IGBT)

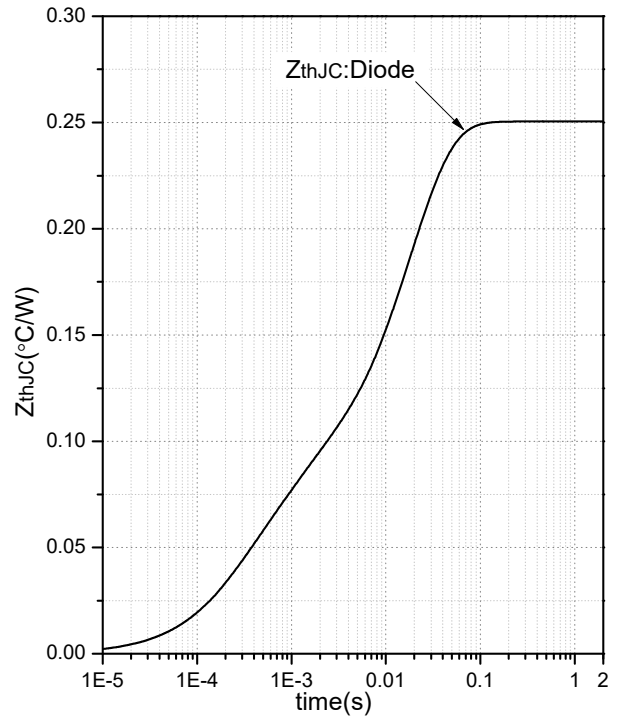


Fig.10 Transient Thermal Impedance (Diode)

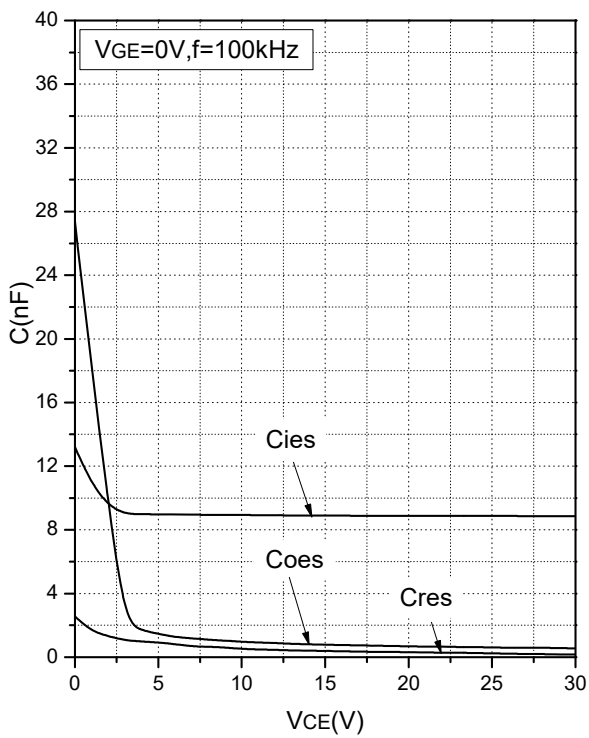


Fig.11 Capacitance Characteristics

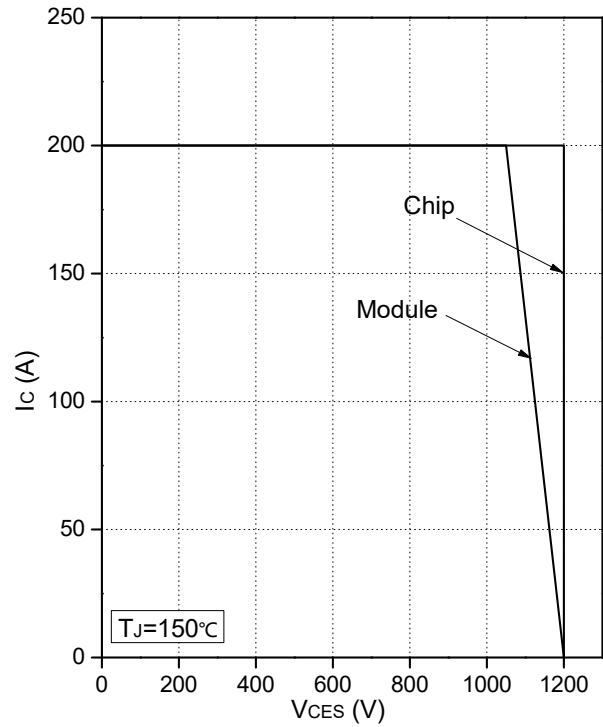
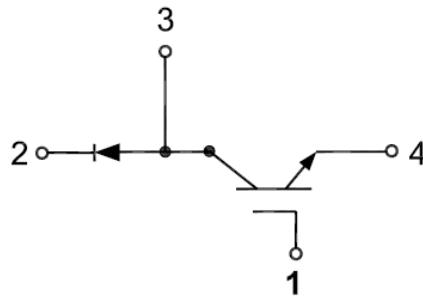


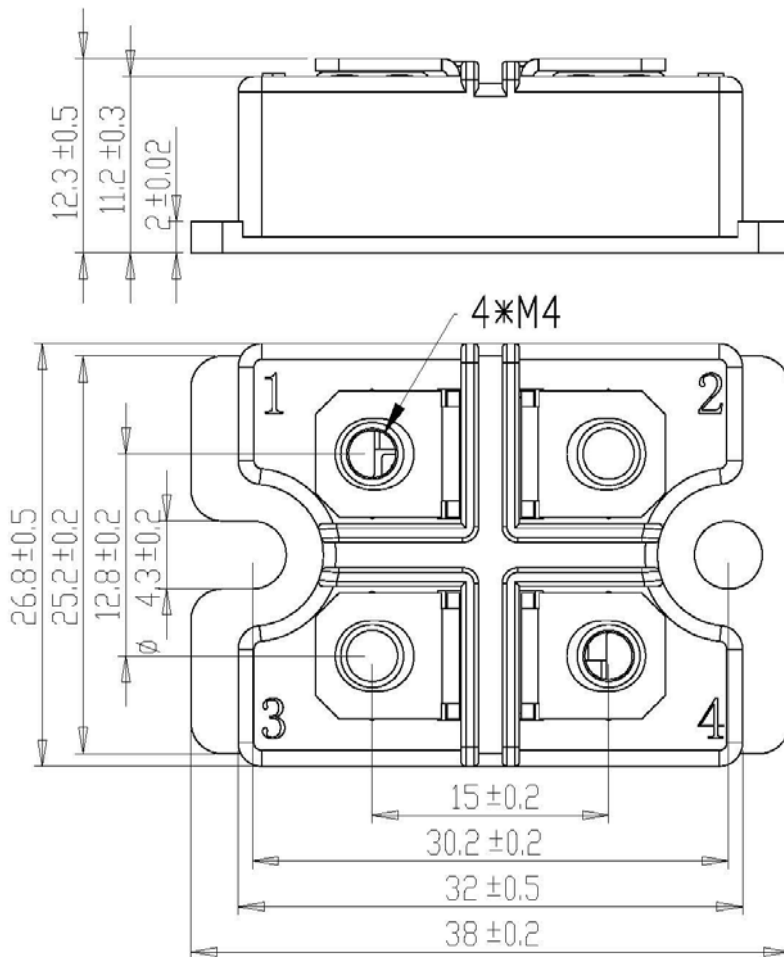
Fig.12 Reverse Bias Safe Operation Area (RBSOA)



Internal Circuit:



Package Outline (Unit: mm):





Date	Revision	Notes
08/17/2023	A	Final Version

Announcement

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